

Corres. and Mail  
**BOX AF**

**RESPONSE UNDER 37. CFR 1.116**  
**EXPEDITED PROCEDURE**  
**EXAMINING GROUP 1752**

AF

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

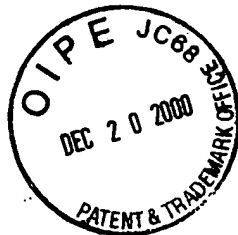
13/12/01

In re application of

Hiroshi TAKANASHI et al.

Serial No. 09/262,077

Filed March 4, 1999



Docket No. 01497/FP/TOK-16-US/YH

Group Art Unit 1752

Examiner S. Lee

NEGATIVE-WORKING PHOTSENSITIVE :  
RESIN COMPOSITION AND  
PHOTOSENSITIVE RESIN PLATE USING :  
THE SAME

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEE FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975.

### RESPONSE TO FINAL REJECTION

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

This is in response to the Final Rejection dated September 20, 2000.

### REMARKS

Favorable reconsideration is respectfully requested.

The claims are 6 to 9.

Claims 6 to 9 have been rejected under 35 U.S.C. 103(a) as being unpatentable over Pine (U.S. 4,361,640).

This rejection is respectfully traversed.

In claim 6 of the present application, component (E) is defined as being at least one member selected from compounds of the formula (I), i.e., R<sup>1</sup>-X, but not limited to p-toluenesulfonamide and o-toluenesulfonamide. In support of such claim, there is submitted herewith a Declaration under 37 C.F.R. 1.132 of H. Takanashi, the first named inventor herein,

RECEIVED  
FEB 22 2001  
TECHNOLOGY CENTER 1700